



广泛应用于太阳能电池等行业。
Widely used in solar cells and other industries.

本机切缝细、热影响区小、切口边缘平整光滑、无裂纹。可以在 AutoCAD、CorelDRAW 中绘制图形导入后进行加工；专用控制软件使程序的编辑和修改简便，实时显示运动轨迹。配备吸尘、CCD 监视系统及真空吸附系统。

This machine with small slits, small heat affected zone, slit edge smooth, no cracks. Can be drawn in AutoCAD, CorelDRAW after importing graphics processing; dedicated control software makes editing and modification of the program easy, real-time display show the motion track. Equipped with vacuum, CCD monitoring and vacuum adsorption system.

- 激光划线宽度细，切割断面整齐，边缘平整光滑。
- 可选配高精度 CCD 视觉定位系统，高速振镜划片，划片速度快。
- 可选配料盒自动传输、电池片自动上料、自动定位、自动划片、成品自动装盒等系统，自动化程度高。
- Small scribing width, the cut section of the cell sheet is more neat, and the edge is smoother.
- Optional high-precision CCD visual positioning system, high-speed galvanometer dicing, fast dicing speed.
- Automatic transfer of optional ingredient boxes, automatic feeding of battery sheets, automatic positioning, automatic dicing, automatic loading of finished tablets Such as the system, High degree of automation.

适用于单晶硅、多晶硅、非晶硅太阳能电池划片，陶瓷、金刚石的切割，硅、锗、砷化镓和半导体基片、半导体器件和集成电路的氧化陶瓷基片（如陶瓷基板）划片；薄金属模板的精密切割、打孔，SMT 贴片机模板的切割。

It is suitable for monocrystalline silicon, polycrystalline silicon, amorphous silicon solar cell dicing, ceramic, diamond cutting, oxide ceramics for silicon, germanium, gallium arsenide and semiconductor substrates, semiconductor devices and integrated circuits substrate (such as ceramic substrate) dicing; precision cutting and punching of thin metal template, SMT stickers cutting of the tablet template.

性能 / 型号	Performance/model	SK-SCF20	SK-SCF30	SK-SCUV3	SK-SCUV5
最大输出功率	Max.Output power	20W	30W	3W	5W
激光波长	Wavelength	1064nm		355nm	
冷却方式	Cooling	风冷 Air		水冷 Water	
最大划片速度	Max.scribing speed	200mm/s			
划片精度	Scribing accuracy	±0.5%			
划片线宽	Scribing line width	≤30μm		≤15μm	
供电电源	Power supply	AC220V±10%/1PH/50Hz			
机器尺寸 (长*宽*高)	Machine size (L*W*H)	1250*700*1700mm			
机器重量	Machine weight	200Kg			